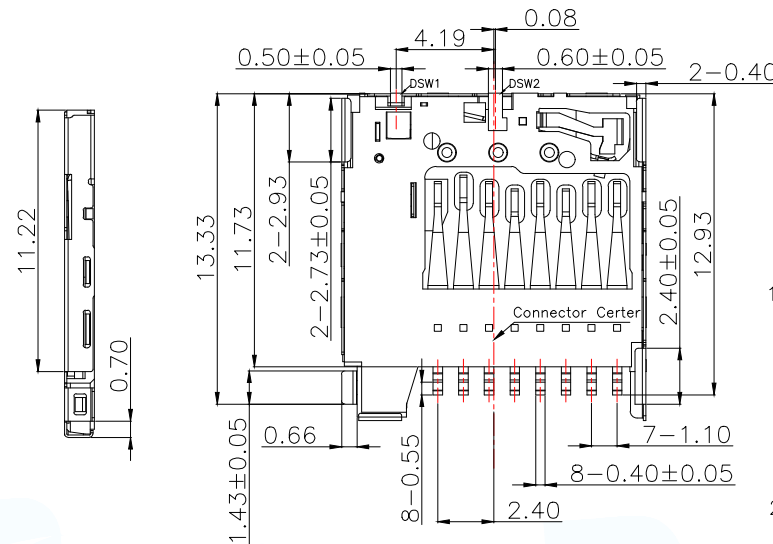


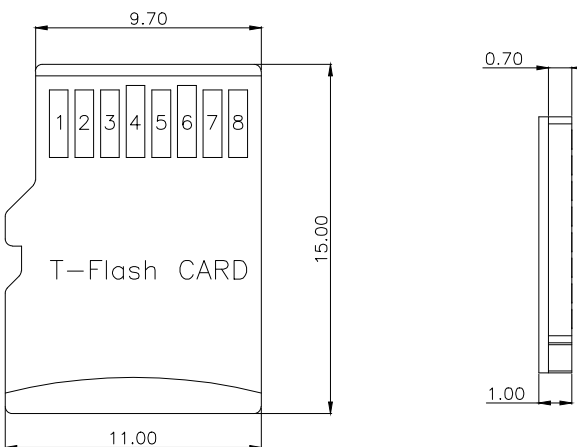
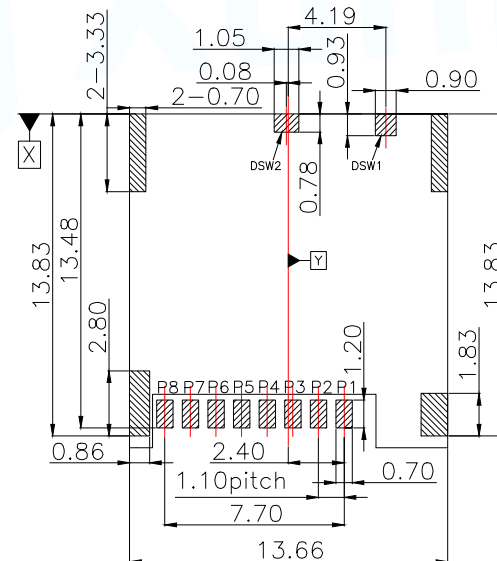
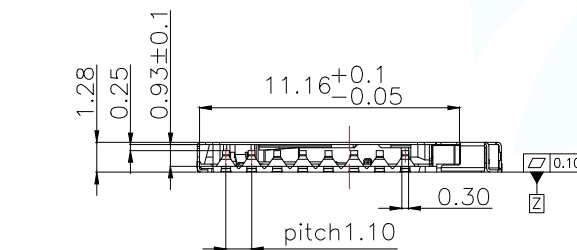
1.MATERIAL:

- 1.1 Insulator: High Temperature Thermoplastic,
LCP SZ6505HF black UL94V-0.
- 1.2 Terminal: Phosphor Bronze (C5210-H, T=0.15mm) 
- 1.3 Shell: SUS301-3/4H T=0.10mm
- 1.4 Spring: SUS301 L=9.80mm
- 1.5 Slider: PPA black 
- 1.6 Drawbar: SUS304-H, L=3.85mm

2.1 Terminal: Plated 80u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 1u"min AU over Ni on solder area
2.2 Shell: Plated 1u"min AU overll 50u"min Ni

3.1 Current Rating :0.5A AC/DC max.
3.2 Voltage Rating :12V AC/DC
3.3 Ambient Temperature Range : -40°C~+85°C
3.4 Ambient Humidity Range :95% R.H. Max.
3.5 Contact Resistance:100mΩ max.
3.6 Insulation Resistance:1000MΩ min./500VDC
3.7 Durability:5000 cycles

PIN NO.	NAME	YTYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLK	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DATO	I/O/PP	DATE LINE(BITO)
8	DAT1	I/O/PP	DATE LINE(DIT1)



WITHOUT CARD	OPEN	 DSW1 DSW2
INSERTING CARD	CLOSE	 DSW1 DSW2

 PAD AREA
 KEEP OUT AREA
 GND PATTERN ONLY



东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd



TITLE:	Micro SD push push 1.28H
--------	--------------------------

PAR	TF-108-ARP10	
DWN		
CHKD		
APVD		
SCALE:1:1	UNIT:MM	
SIZE:A4	SHEET:1F1	REV:A

MANUFACTURE DWG

UNLESS OTHERWISE
SPECIFIED TOLERANCES

--	--

DECIMALS:	
-----------	--

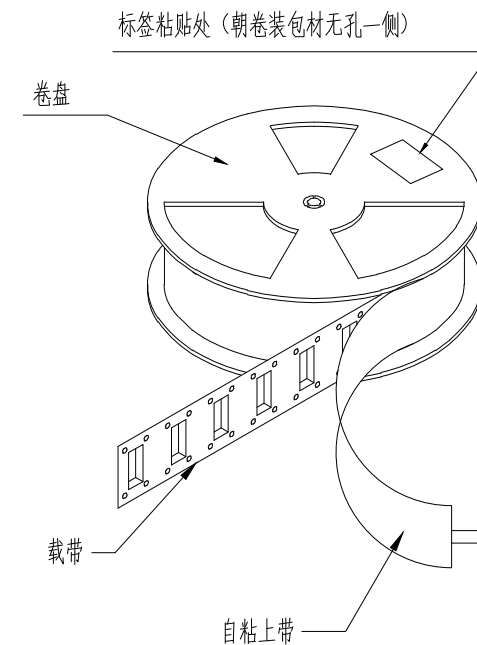
ANGLES

.X:±0.35

 $\chi: \pm 2^\circ$

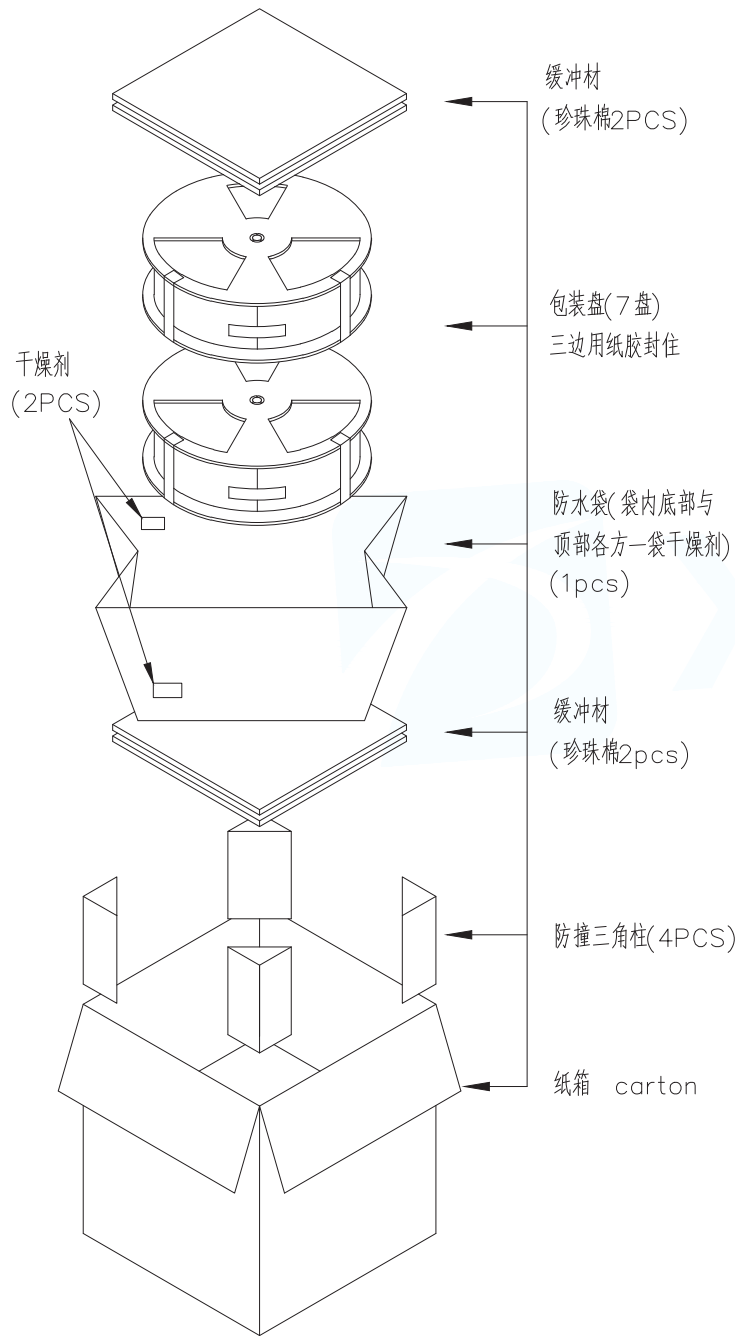
CUSTOMER COPY

SIZE:A4	SHEET:1F1	REV:A
---------	-----------	-------



PART NAME	Micro SD H1.28 CARD包装规范
QUANTITY OF PER TRAY	2400PCS/TRAY
QUANTITY OF PER CARTON	7*2400=16800PCS/CARTON

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD push push 1.28H		
			PAR	TF-108-ARP10	
DECIMALS:	ANGLES:		DWN		
.X:±0.35	X.*:±2°		CHKD		
.XX:±0.20	X.X*:±1°		APVD		
.XXX:±0.10	X.XX*:±0.5°	SCALE 1:1	UNIT:MM		
		CUSTOMER COPY	SIZE:A4	SHEET:1F1	REV:A



10	干燥剂	2PCS
9	三角压线条	4PCS
8	珍珠棉	4PCS
7	纸箱	1PCS
6	保护带	7PCS
5	自粘上带	38.72M*7
4	卷盘	7PCS
3	PE防水袋	1PCS
2	载带	7pcs
1	Micro SD H1.28 CARD	16800PCS

备注:

1. 每卷载带前后各留 10 个空格不使用.
2. 每卷载带包装2400PCS 产品.
3. 以自粘上带覆盖经包装机冷封包装.
4. 以保护带覆盖于外圈再以胶带固定并粘贴卷盘标签.
5. 将 7 卷包装好的产品放入PE 防水袋,
防水袋的上下各放置 2PCS 珍珠棉, 以胶带固定PE 防水袋.
6. 将包装好的 7 卷产品放入纸箱, 四周用三角压线条固定;
外箱用胶带呈 “工” 字形封口.
7. 外箱标签的贴法请参照客户资料.

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD push push 1.28H	
			PAR	TF-108-ARP10
			DWN	
			CHKD	
			APVD	
DECIMALS:	ANGLES:	SCALE1:1	UNIT: MM	
.X: ±0.25	X.: ±2°	CUSTOMER	COPY	REV: A
.XX: ±0.15	X.X: ±1°	SIZE: A4	SHEET: 1F1	
.XXX: ±0.05	X.XX: ±0.5°			